

Electronic Patent Application Fee Transmittal

Application Number:	10567733			
Filing Date:	10-Feb-2006			
Title of Invention:	Method for forming film, method for manufacturing semiconductor device, semiconductor device and substrate treatment system			
First Named Inventor/Applicant Name:	Kohei Kawamura			
Filer:	Marvin Jay Spivak/Yuriko Stankich			
Attorney Docket Number:	285995US26PCT			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Petition fee- 37 CFR 1.17(h) (Group III)	1464	1	130	130
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130